

SOT684-6

plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package type industry code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-11-2002

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	0.8	-	0.85	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	56	-	

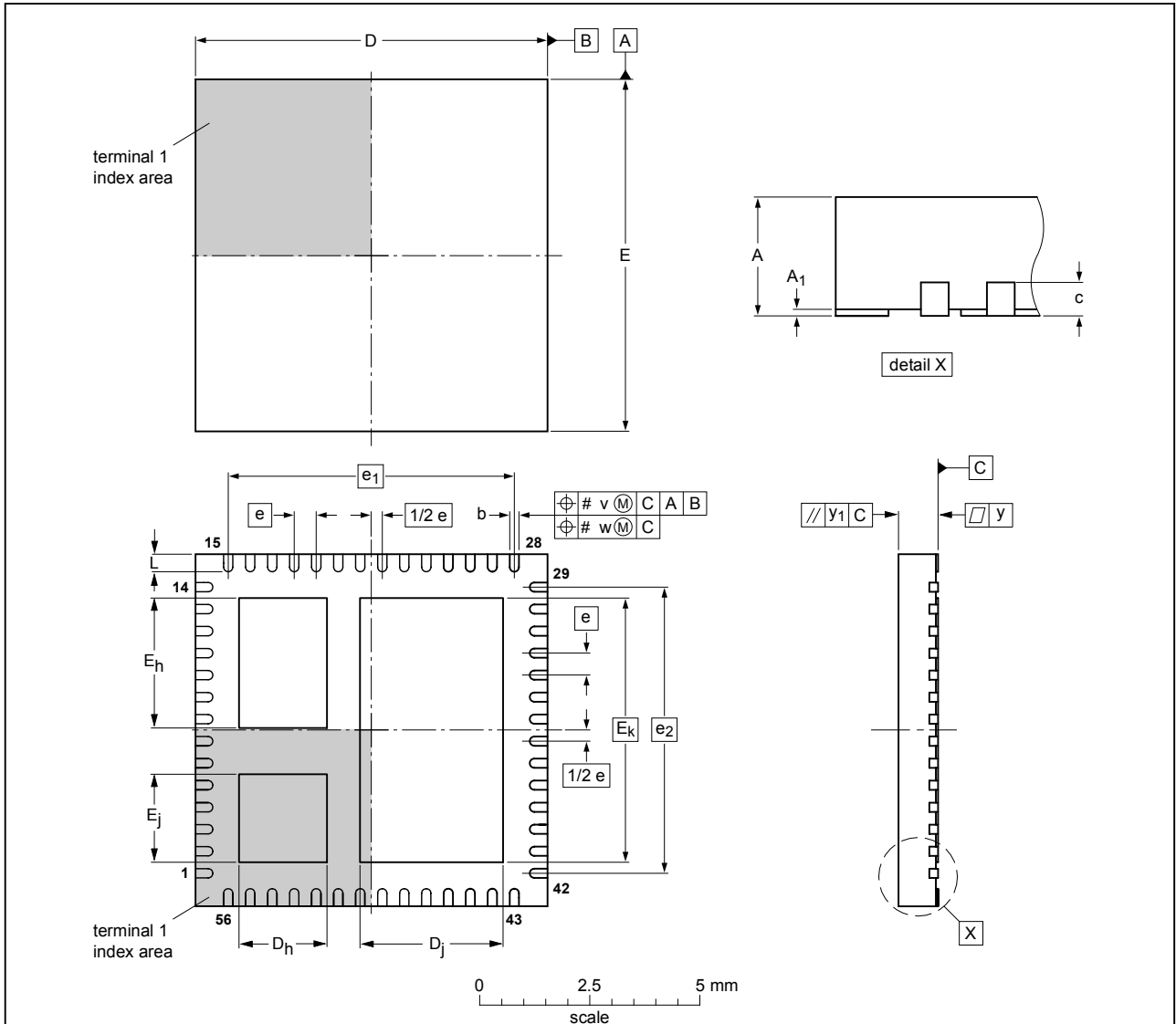


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2. Package outline

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A ⁽¹⁾	A ₁	b	c	D ⁽¹⁾	D _h	D _j	E ⁽¹⁾	E _h	E _j	E _k	e	e ₁	e ₂	L	v	w	y	y ₁
mm	max	1.00	0.05	0.30	8.1	2.15	3.40	8.1	3.10	2.15	6.15	0.5	6.5	6.5	0.5	0.1	0.05	0.05	0.1
	nom	0.85	0.02	0.21	8.0	2.00	3.25	8.0	2.95	2.00	6.00	0.5	6.5	6.5	0.4	0.1	0.05	0.05	0.1
	min	0.80	0.00	0.18	7.9	1.85	3.10	7.9	2.80	1.85	5.85	0.5	6.5	6.5	0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT684-6	---	---	---		08-06-06 08-06-19

Fig. 1. Package outline HVQFN56 (SOT684-6)

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3. Legal information

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